

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application. Additions to amended claims are underlined. Deletions to amended claims are bracketed and struck through.

1. (Presently amended) A selectively electroplated structure [article] comprising a directly electroplateable resin (DER).
2. (Presently amended) A selectively electroplated structure [article] comprising a material having a resistivity greater than .001 ohm-cm. positioned contiguous to a directly electroplateable resin (DER).
3. (Presently amended) A selectively electroplated structure, said structure having an exterior surface, a first portion of said exterior surface being defined by a material having resistivity greater than .001 ohm-cm. and a second portion of said exterior surface defined by a metal-based electrodeposit directly contacting a directly electroplateable resin (DER).
4. (Presently amended) A selectively electroplated structure as in claim 3, wherein said material defining said first portion of said exterior surface is further characterized as being devoid of an electrodeposit growth rate accelerator. [~~said structure being defined by two or more exterior surfaces, at least a portion of a first of said exterior surfaces being defined by a material devoid of an electrodeposit growth rate accelerator and having resistivity greater than .001 ohm-cm., and at least a portion of a second of said exterior surfaces being defined by a metal-based electrodeposit directly contacting a DER.~~]
5. (Presently amended) A selectively electroplated structure [article] produced by the process as follows;
 - producing an article having multiple [~~defined by one or more~~] exterior [surfaces] surface portions, at least a first [~~portion~~] of any of said exterior [surfaees] surface portions being [~~formed~~] defined by a directly electroplateable resin (DER), and at least a second [~~portion~~] of any of said exterior [surfaces] surface portions being formed by a material devoid of an electrodeposit growth rate accelerator and having resistivity greater than .001 ohm-cm.,
 - exposing said first and second exterior [surfaces] surface portions to an electroplating solution to thereby electrodeposit metal onto [~~at least one of the surface portions formed by the DER~~] said first portion.
6. (Presently amended) An intermediate article of manufacture comprising multiple surface portions, a first of said surface portions being defined by a directly electroplateable resin (DER), and a second of said multiple surface regions being formed by a material having a resistivity greater than .001 ohm-cm. and devoid of an electrodeposit growth rate accelerator [~~a DER wherein the exterior surface of said article is selectively electroplated~~].

7. (Newly presented) A selectively electroplated structure, said structure characterized by having multiple surface regions, a first of said surface regions being defined by an electrodeposit in direct contact with a directly electroplateable resin (DER).
8. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin has been formed by injection molding.
9. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin has been formed by printing.
10. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin has been formed by extrusion.
11. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin comprises an elastomer.
12. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin comprises carbon black.
13. (Newly presented) The selectively electroplated structure of claim 7 wherein said directly electroplateable resin comprises a source of sulfur.
14. (Newly presented) A selectively electroplated structure as in claim 7 wherein said directly electroplateable resin comprises an adhesion promoter.
15. (Newly presented) A selectively electroplated structure as in claim 7 wherein said electrodeposit forms at least a portion of an antenna.
16. (Newly presented) A selectively electroplated structure as in claim 7 wherein said electrodeposit forms at least a portion of an electrical circuit.
17. (Newly presented) A selectively electroplated structure as in claim 7 wherein said electrodeposit extends through a hole in said article.
18. (Newly presented) A selectively electroplated structure as in claim 7 used to achieve electrical interconnection among multiple photovoltaic cells.
19. (Newly presented) A selectively electroplated structure as in claim 7 used for storage of electrical energy.
20. (Newly presented) A selectively electroplated structure as in claim 7 used as at least a portion of an electrical capacitor.
21. (Newly presented) A selectively electroplated structure as in claim 7 used as an electrode.

22. (Newly presented) A selectively electroplated structure as in claim 7 wherein a second of said multiple surface regions is formed by an insulating stopoff material, said stopoff material being printed.

23. (Newly presented) A selectively electroplated structure as in claim 7 wherein a second of said multiple surface regions comprises an elastomer.

24. (Newly presented) A selectively electroplated structure as in claim 7 characterized as being a substantially planar web.

25. (Newly presented) A selectively electroplated structure as in claim 7 wherein said electrodeposit is intended to impart a primarily functional attribute.